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## REDLINE VERSION

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### **Industriell processtyrning – Integration av fältenheter (FDI) – Del 1: Översikt**

*Field device integration (FDI) –  
Part 1: Overview*

En så kallad ”Redline version” (RLV) innehåller både den fastställda IEC-standarden och en ändringsmarkerad standard. Alla tillägg och borttagningar sedan den tidigare utgåvan är markerade med färg. Med en RLV sparar du mycket tid när du ska identifiera och bedöma aktuella ändringar i standarden. SEK Svensk Elstandard kan bara ge ut en RLV i de fall den finns tillgänglig från IEC.



IEC 62769-1

Edition 2.0 2021-02  
REDLINE VERSION

# INTERNATIONAL STANDARD



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## Field device integration (FDI) – Part 1: Overview

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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ICS 25.040.40; 35.100.05

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## CONTENTS

FOREWORD .....	4
INTRODUCTION .....	2
1 Scope .....	8
2 Normative references .....	8
3 Terms, definitions, abbreviated terms and <del>acronyms</del> conventions .....	9
3.1 Terms and definitions .....	9
3.2 IEC TR 62541-1 terms (OPC UA) .....	12
3.3 IEC 62541-3 (OPC UA) terms .....	12
3.4 IEC 62541-4 (OPC UA) terms .....	13
3.5 IEC 62541-5 (OPC UA) terms .....	13
3.6 IEC 62541-100 (OPC UA for Devices) terms .....	13
3.7 Abbreviated terms .....	13
3.8 Conventions .....	14
4 Background .....	14
4.1 Motivation .....	14
4.2 Electronic Device Description Language (EDDL) .....	15
4.3 Field Device Tool (FDT <sup>®</sup> ) .....	15
4.4 OPC Unified Architecture (OPC UA) .....	16
5 Architecture .....	16
5.1 Overview .....	16
5.2 FDI Packages .....	17
5.3 FDI Client .....	18
5.4 FDI Server .....	18
5.5 FDI Communication Server .....	19
5.6 User Interface tiering .....	19
5.7 FDI security considerations .....	19
5.8 Redundancy .....	20
6 Deployment .....	20
6.1 Overview .....	20
6.2 Engineering, operator and maintenance stations .....	21
6.3 FDI Server .....	21
6.4 FDI Communication Servers .....	21
6.5 Device Tools .....	21
6.6 Third-party Tools .....	21
6.7 Handheld Tools .....	21
6.8 Generic OPC UA Clients .....	21
7 FDI Host .....	21
7.1 Overview .....	21
7.2 FDI Host Variants and Entities .....	22
7.3 FDI Host Facets .....	22
8 Life-cycle model .....	23
8.1 Overview .....	23
8.2 Identification mechanism .....	23
8.3 Versioning mechanism .....	24
8.3.1 Version levels .....	24

8.3.2	FDI Technology Version .....	24
8.3.3	Forward compatibility.....	27
Annex A (informative)	FDI life-cycle concept summary.....	29
A.1	General.....	29
A.2	Life-cycle relevant topics (references).....	29
Annex B (informative)	Issue reporting .....	30
Bibliography	.....	31
Figure 1	– FDI architecture diagram.....	17
Figure 2	– Typical deployment scenario .....	20
Figure 3	– FDI Technology Version dependencies .....	25
Table 1	– FDI Host Variants and possible Facets .....	22
Table 2	– FDI Host Facets and related FDI Entities.....	23
Table 3	– Summary of influences on the FDI Technology Version .....	27
Table 4	– Combinations of Minor Versions that require special handling .....	27
Table A.1	– Life-cycle aspects as part of the FDI technology .....	29
Table A.2	– Life-cycle aspects as part of products and services provided with the FDI technology .....	29

# INTERNATIONAL ELECTROTECHNICAL COMMISSION

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## FIELD DEVICE INTEGRATION (FDI) –

### Part 1: Overview

#### FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
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**This redline version of the official IEC Standard allows the user to identify the changes made to the previous edition IEC 62769-1:2015. A vertical bar appears in the margin wherever a change has been made. Additions are in green text, deletions are in strikethrough red text.**

International Standard IEC 62769-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) digital signature now include trusted timestamping for long term validation of FDI Package;
- c) support of new protocols.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/758/FDIS	65E/768/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

**IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.**

## INTRODUCTION

The IEC ~~62657~~ 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

~~The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents concerning~~

- ~~a) method for the supplying and installation of device-specific functionalities, see Patent Family DE10357276;~~
- ~~b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;~~
- ~~c) methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;~~
- ~~d) extensible device object model, see Patent Family US12/893,680.~~

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Flachsmarktstrasse 8, 32825 Blomberg  
Germany~~
- ~~c) Fisher Controls International LLC  
John Dilger, Emerson Process Management LLLP  
301 S. 1<sup>st</sup> Avenue, Marshalltown, Iowa 50158  
USA~~

~~d) Rockwell Automation Technologies, Inc.  
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Mayfield Heights, Ohio 44124  
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~~ISO ([www.iso.org/patents](http://www.iso.org/patents)) and IEC (<http://patents.iec.ch>) maintain on-line data bases of patents relevant to their standards. Users are encouraged to consult the data bases for the most up to date information concerning patents.~~



# FIELD DEVICE INTEGRATION (FDI) –

## Part 1: Overview

### 1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

~~IEC 61804 (all parts), Function blocks (FB) for process control and Electronic Device Description Language (EDDL)~~

~~IEC 62453 (all parts), Field device tool (FDI<sup>®</sup>) interface specification~~

~~IEC 62541 (all parts), OPC Unified Architecture~~

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

~~IEC 62769-2, Field Device Integration (FDI) – Part 2: FDI Client~~

~~NOTE IEC 62769-2 is technically identical to FDI-2022[4]<sup>1</sup>~~

~~IEC 62769-3, Field Device Integration (FDI) – Part 3: FDI Server~~

~~NOTE IEC 62769-3 is technically identical to FDI-2023. [5]~~

~~IEC 62769-4:2015, Field Device Integration (FDI) – Part 4: FDI Packages~~

~~NOTE IEC 62769-4 is technically identical to FDI-2024. [6]~~

~~IEC 62769-5:2015, Field Device Integration (FDI) – Part 5: FDI Information Model~~

~~NOTE IEC 62769-5 is technically identical to FDI-2025. [7]~~

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<sup>1</sup> Numbers in square brackets refer to the Bibliography.

~~IEC 62769-6:2015, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*~~

~~NOTE – IEC 62769-6 is technically identical to FDI-2026. [8]~~

~~IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*~~

~~NOTE – IEC 62769-7 is technically identical to FDI-2027. [9]~~

~~ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*~~

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## Industriell processtyrning – Integration av fältenheter (FDI) – Del 1: Översikt

*Field device integration (FDI) –  
Part 1: Overview*

Som svensk standard gäller europastandarden EN IEC 62769-1:2021. Den svenska standarden innehåller den officiella engelska språkversionen av EN IEC 62769-1:2021.

### Nationellt förord

Europastandarden EN IEC 62769-1:2021

består av:

- **europastandardens ikraftsättningsdokument**, utarbetat inom CENELEC
- **IEC 62769-1, Second edition, 2021 - Field device integration (FDI) - Part 1: Overview**

utarbetad inom International Electrotechnical Commission, IEC.

Tidigare fastställd svensk standard SS-EN 62769-1, utgåva 1, 2016, gäller ej fr o m 2024-03-12.

### *Standarder underlättar utvecklingen och höjer elsäkerheten*

Det finns många fördelar med att ha gemensamma tekniska regler för bl a mätning, säkerhet och provning och för utförande, skötsel och dokumentation av elprodukter och elanläggningar.

Genom att utforma sådana standarder blir säkerhetsfordringar tydliga och utvecklingskostnaderna rimliga samtidigt som marknadens acceptans för produkten eller tjänsten ökar.

Många standarder inom elområdet beskriver tekniska lösningar och metoder som åstadkommer den elsäkerhet som föreskrivs av svenska myndigheter och av EU.

### *SEK är Sveriges röst i standardiseringsarbetet inom elområdet*

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### *Stora delar av arbetet sker internationellt*

Utformningen av standarder sker i allt väsentligt i internationellt och europeiskt samarbete. SEK är svensk nationalkommitté av International Electrotechnical Commission (IEC) och Comité Européen de Normalisation Electrotechnique (CENELEC).

Standardiseringsarbetet inom SEK är organiserat i referensgrupper bestående av ett antal tekniska kommittéer som speglar hur arbetet inom IEC och CENELEC är organiserat.

Arbetet i de tekniska kommittéerna är öppet för alla svenska organisationer, företag, institutioner, myndigheter och statliga verk. Den årliga avgiften för deltagandet och intäkter från försäljning finansierar SEKs standardiseringsverksamhet och medlemsavgift till IEC och CENELEC.

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Den som deltar i SEKs tekniska kommittéarbete har möjlighet att påverka framtida standarder och får tidig tillgång till information och dokumentation om utvecklingen inom sitt teknikområde. Arbetet och kontakterna med kollegor, kunder och konkurrenter kan gynnsamt påverka enskilda företags affärsutveckling och bidrar till deltagarnas egen kompetensutveckling.

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EUROPEAN STANDARD

**EN IEC 62769-1**

NORME EUROPÉENNE

EUROPÄISCHE NORM

March 2021

ICS 35.100; 25.040.40; 35.100.05

Supersedes EN 62769-1:2015 and all of its amendments  
and corrigenda (if any)

English Version

## Field Device Integration (FDI) - Part 1: Overview (IEC 62769-1:2021)

Intégration des appareils de terrain (FDI) - Partie 1: Vue  
d'ensemble  
(IEC 62769-1:2021)

Feldgeräteintegration (FDI) - Teil 1: Überblick  
(IEC 62769-1:2021)

This European Standard was approved by CENELEC on 2021-03-12. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
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Ref. No. EN IEC 62769-1:2021 E

SEK Svensk Elstandard

SS-EN IEC 62769-1, utg 2:2021

## **European foreword**

The text of document 65E/758(F)/FDIS, future edition 2 of IEC 62769-1, prepared by SC 65E “Devices and integration in enterprise systems” of IEC/TC 65 “Industrial-process measurement, control and automation” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-1:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2021-12-12 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2024-03-12 document have to be withdrawn

This document supersedes EN 62769-1:2015 and all of its amendments and corrigenda (if any).

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### **Endorsement notice**

The text of the International Standard IEC 62769-1:2021 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61804-3	NOTE Harmonized as EN IEC 61804-3
IEC 61804-4	NOTE Harmonized as EN IEC 61804-4
IEC 61804-5	NOTE Harmonized as EN IEC 61804-5
IEC 62443 series	NOTE Harmonized as EN IEC 62443 series
IEC 62453 series	NOTE Harmonized as EN 62453 series
IEC 62541 series	NOTE Harmonized as EN IEC 62541 series
IEC 62769-2	NOTE Harmonized as EN 62769-2
IEC 62769-3	NOTE Harmonized as EN 62769-3
IEC 62769-4	NOTE Harmonized as EN 62769-4
IEC 62769-5	NOTE Harmonized as EN 62769-5
IEC 62769-6	NOTE Harmonized as EN 62769-6
IEC 62769-7	NOTE Harmonized as EN 62769-7

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC/TR 62541-1	-	OPC Unified Architecture - Part 1: Overview and concepts	CLC/TR 62541-1	-
IEC 62541-3	-	OPC Unified Architecture - Part 3: Address Space Model	EN IEC 62541-3	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN IEC 62541-4	-
IEC 62541-5	-	OPC Unified Architecture - Part 5: Information Model	EN IEC 62541-5	-
IEC 62541-100	-	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	-

## CONTENTS

FOREWORD .....	4
INTRODUCTION .....	6
1 Scope .....	7
2 Normative references .....	7
3 Terms, definitions, abbreviated terms and conventions .....	7
3.1 Terms and definitions .....	7
3.2 IEC TR 62541-1 terms (OPC UA) .....	10
3.3 IEC 62541-3 (OPC UA) terms .....	10
3.4 IEC 62541-4 (OPC UA) terms .....	11
3.5 IEC 62541-5 (OPC UA) terms .....	11
3.6 IEC 62541-100 (OPC UA for Devices) terms .....	11
3.7 Abbreviated terms .....	12
3.8 Conventions .....	12
4 Background .....	12
4.1 Motivation .....	12
4.2 Electronic Device Description Language (EDDL) .....	13
4.3 Field Device Tool (FDT <sup>®</sup> ) .....	13
4.4 OPC Unified Architecture (OPC UA) .....	14
5 Architecture .....	14
5.1 Overview .....	14
5.2 FDI Packages .....	15
5.3 FDI Client .....	16
5.4 FDI Server .....	16
5.5 FDI Communication Server .....	17
5.6 User Interface tiering .....	17
5.7 FDI security considerations .....	17
5.8 Redundancy .....	18
6 Deployment .....	18
6.1 Overview .....	18
6.2 Engineering, operator and maintenance stations .....	19
6.3 FDI Server .....	19
6.4 FDI Communication Servers .....	19
6.5 Device Tools .....	19
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6.8 Generic OPC UA Clients .....	19
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7.1 Overview .....	19
7.2 FDI Host Variants and Entities .....	20
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8 Life-cycle model .....	21
8.1 Overview .....	21
8.2 Identification mechanism .....	21
8.3 Versioning mechanism .....	22
8.3.1 Version levels .....	22



8.3.2	FDI Technology Version .....	22
8.3.3	Forward compatibility.....	25
Annex A (informative)	FDI life-cycle concept summary.....	27
A.1	General.....	27
A.2	Life-cycle relevant topics (references).....	27
Annex B (informative)	Issue reporting .....	28
Bibliography.....		29
Figure 1 – FDI architecture diagram.....		15
Figure 2 – Typical deployment scenario .....		18
Figure 3 – FDI Technology Version dependencies .....		23
Table 1 – FDI Host Variants and possible Facets .....		20
Table 2 – FDI Host Facets and related FDI Entities.....		21
Table 3 – Summary of influences on the FDI Technology Version .....		25
Table 4 – Combinations of Minor Versions that require special handling .....		25
Table A.1 – Life-cycle aspects as part of the FDI technology .....		27
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# INTERNATIONAL ELECTROTECHNICAL COMMISSION

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## FIELD DEVICE INTEGRATION (FDI) –

### Part 1: Overview

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FDIS	Report on voting
65E/758/FDIS	65E/768/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

**IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.**

## INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

## FIELD DEVICE INTEGRATION (FDI) –

### Part 1: Overview

#### 1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*